

Kindly enter the following preliminary amendment in the above-identified patent application, prior to examination.

In the Specification

At page 1, before line 1, please insert the heading and following paragraph:

RELATED APPLICATIONS

A. This application is a divisional application of U.S. Application No. 09/488,647 filed on January 20, 2000, which claims priority to U.S. Application No. 08/853,171 filed on May 8, 1997, now U.S. Patent No. 6,069,017, which is a divisional application of U.S. Application No. 08/396,694, filed March 1, 1995, now U.S. Patent No. 5,661,408.

At page 10, please replace the first paragraph with the following:

C1 In brief overview, and referring to Fig. 1, an embodiment of such an apparatus 10 for the real-time, in-line, electrical characterization of a semiconductor during manufacturing using induced surface photovoltage includes a sensor head assembly 14, supporting electronics 18, and a wafer conveying device 22. In operation, the wafer conveying device 22, such as a conveyor belt, a robotic arm, a wafer chuck or similar device, moves wafers 28, 28' through the manufacturing process and, in one embodiment, beneath the sensor head assembly 14.

[At page 10, please replace the second paragraph with the following:]

Referring to Fig. 2, the sensor head assembly 14 includes a probe head 32 mounted in a bracket 36 on a motorized stage 40. The motorized stage 40 moves the probe head 32 in a vertical direction (arrow z) to adjust vertical position of the probe head 32 with respect to the wafer 28 to within a 0.2 μm accuracy. The mechanical stage 40 is attached to a probe arm 44.